



Beam Abort System

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21 Feb. 2012

✦ Introduction

✦ Optics

✦ Development of Hardware

- Beam Abort Kicker and Pulsed Quadrupole Magnet

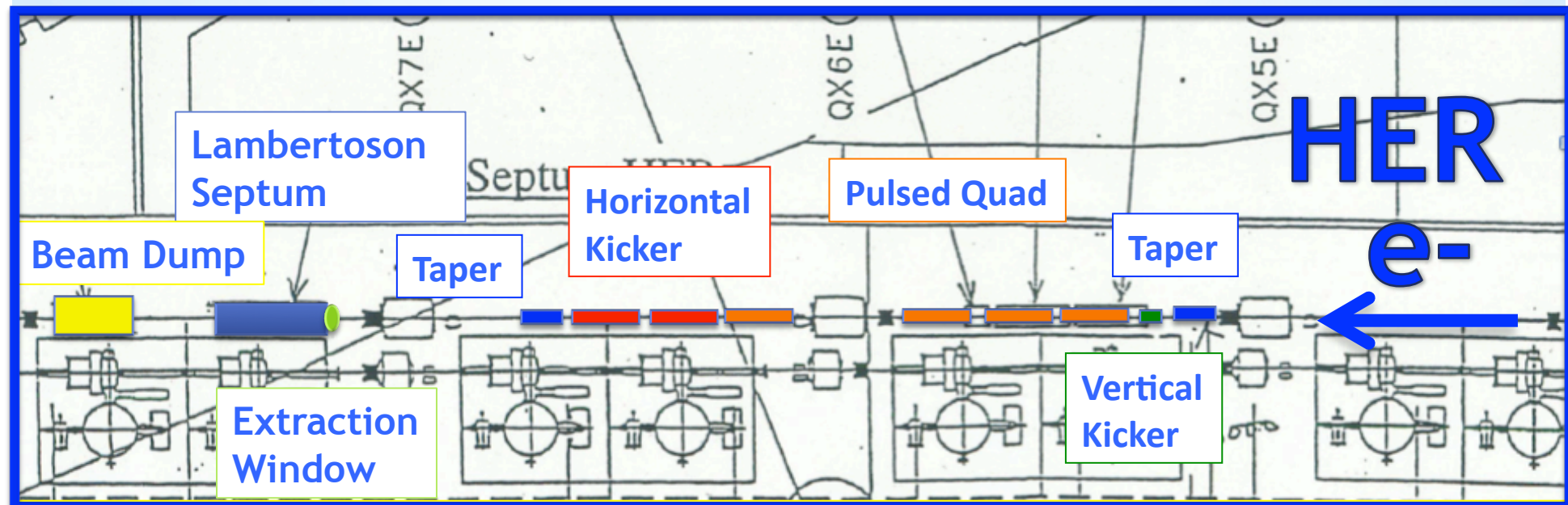
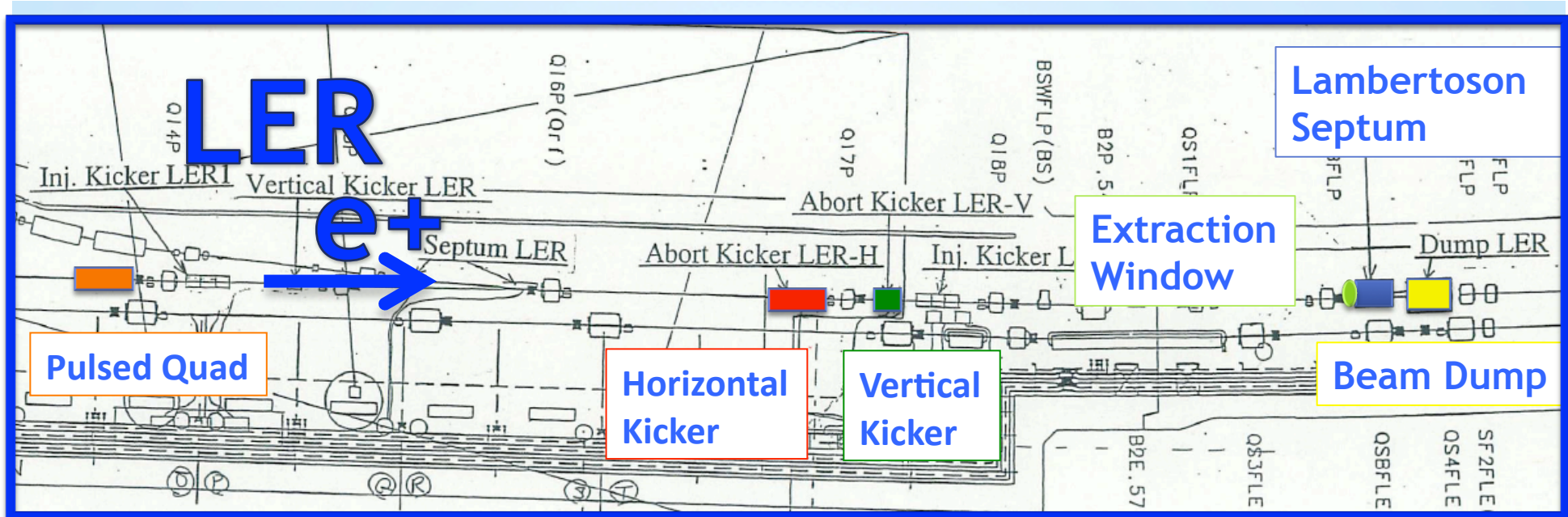
- Power Supply

- Ceramic Chamber

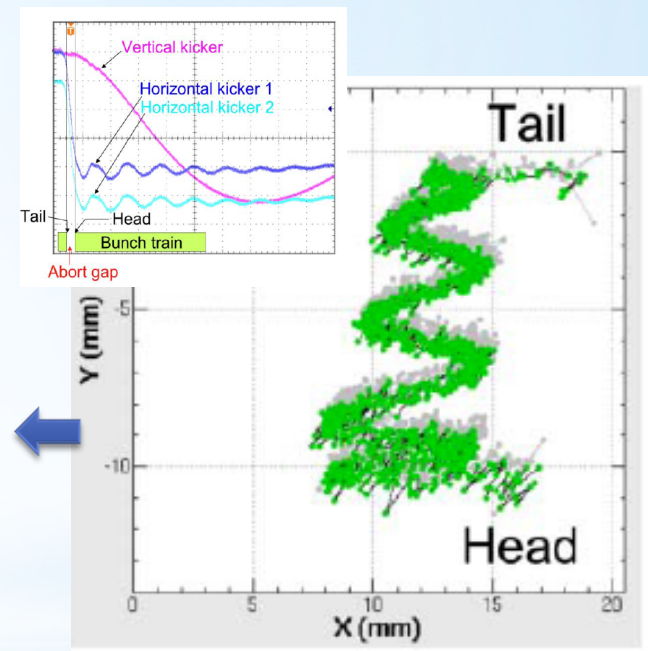
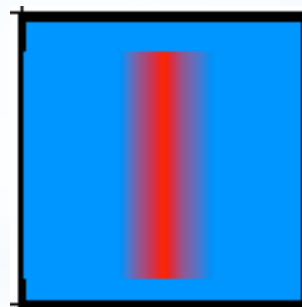
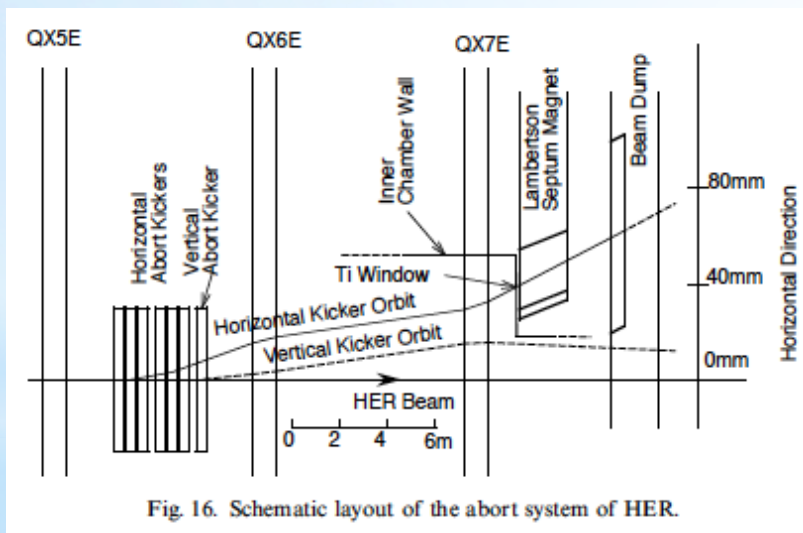
- Extraction Window

✦ Issues and Discussion

Contents



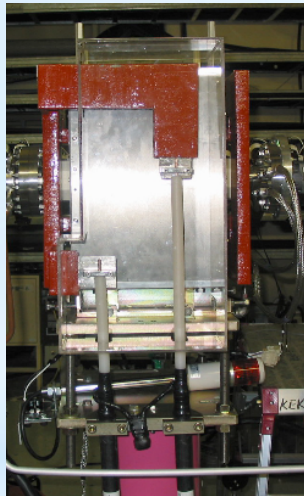
- ★ Very fast rise time (Requirement from RF group)
 - > Abort Gap : $dT < 200\text{nsec}$ (KEKB:500nsec)
- ★ Make the beam size large @ extraction Window
- ★ All or Nothing
 - > One ring use one power supply



Requirements for Beam Abort System



Horizontal

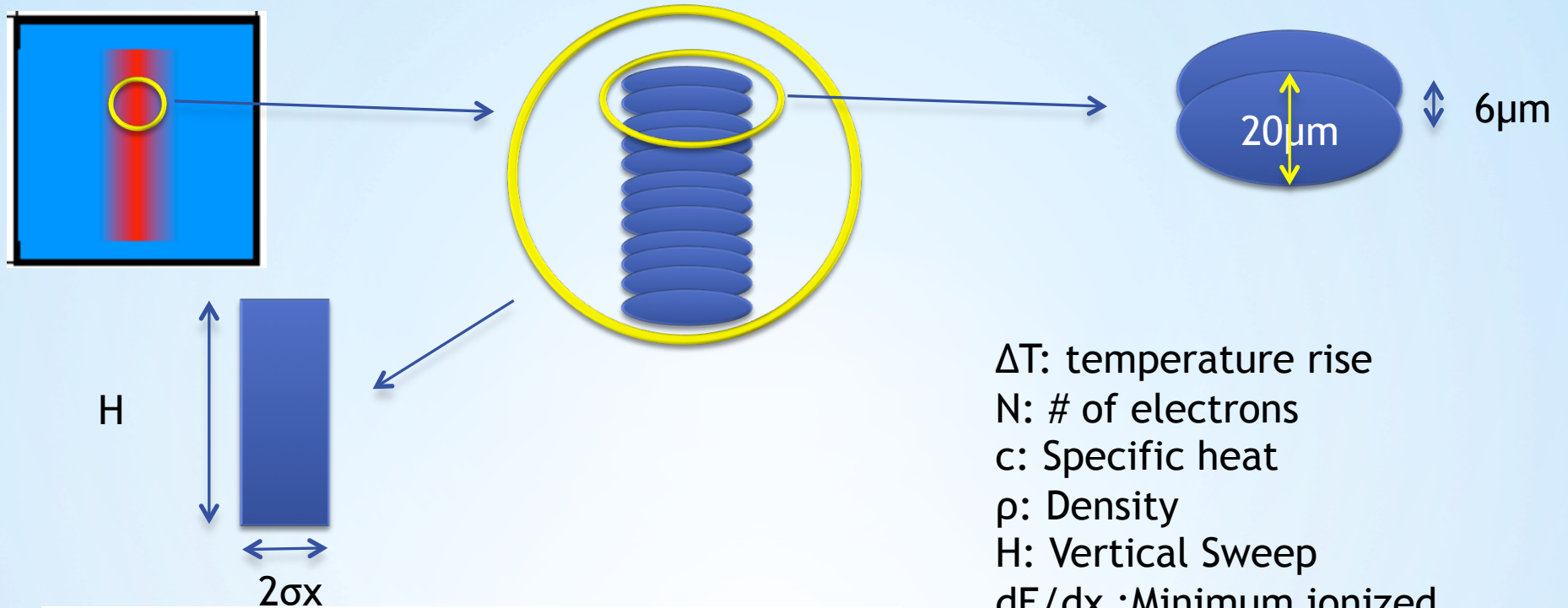


Vertical

	LER	HER
Horizontal Kicker	1	2
Vertical Kicker	1	1
Pulsed Quadrupole	1	4
Lambertson Septum	1	1
Power Supply	1	1
Pulse Compression	2	6
Beam Dump	1	1
Extraction Window	1	1
Water Cooling Ceramic	3	7

- (1) Add Pulsed Quadrupole Magnets to enlarge the beam size @window
- (2) Fast rise time of the Horizontal Kicker magnet (Abort Gap 500nsec -> 200nsec)

Components of abort System



ΔT : temperature rise
 N: # of electrons
 c: Specific heat
 ρ : Density
 H: Vertical Sweep
 dE/dx : Minimum ionized energy deposit
 σ_x : Horizontal Beam size

$$\Delta T = \frac{N}{c} \left(-\frac{1}{\rho} \frac{dE}{dx} \right) \frac{1}{\sqrt{2\pi}\sigma_x H}$$

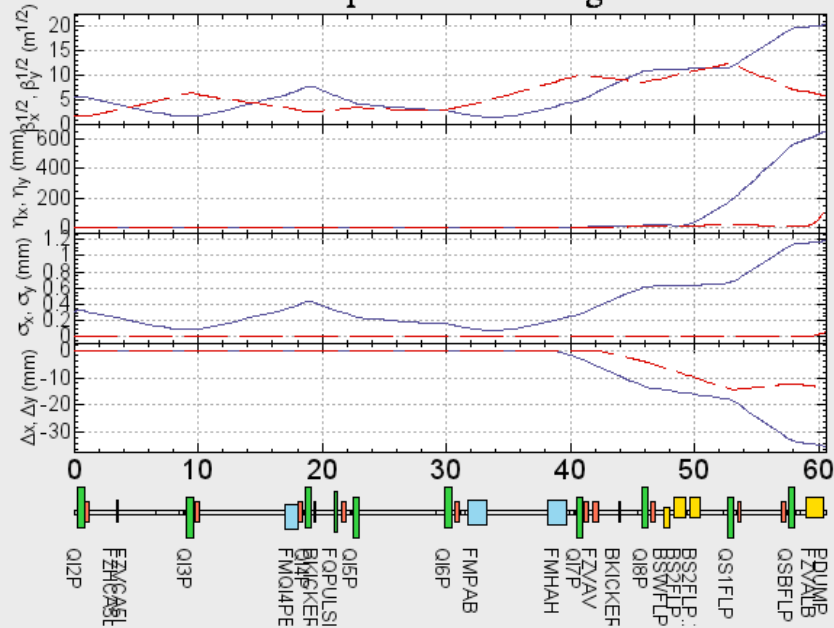
ΔT dose not depend on window thickness. (Lowest order)

Basic Idea

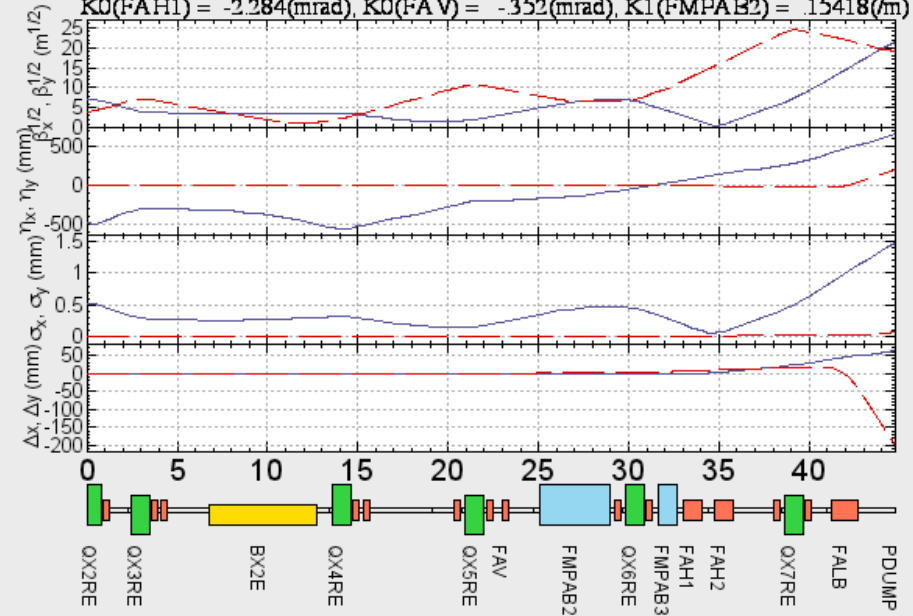
	KEKB (LER)	SKEKB (LER)	SKEKB (HER)
E (GeV)	3.5	4 (4.16)	7 (8.6)
ϵ_x (nm)	24	3.2	4.6
σ_x (mm)@window	0.68	1.22	0.88
Vertical Sweep (mm)	10	10 (15)	10(15)
I (A)	2	3.6	2.6
I/σ_x (A/mm)	3		

Abort System Parameter

LER Abort Optics at the straight section



HER Abort Q+Kicker Optics, $\epsilon_x = 4.6\text{nm}$, $\Delta Y(\text{LB}) = 15000(\text{mm})$
 $KO(\text{FAH1}) = -2.284(\text{mrad})$, $KO(\text{FAV}) = -3.52(\text{mrad})$, $K1(\text{FMPAB2}) = 15418(\text{m})$



LER

HER

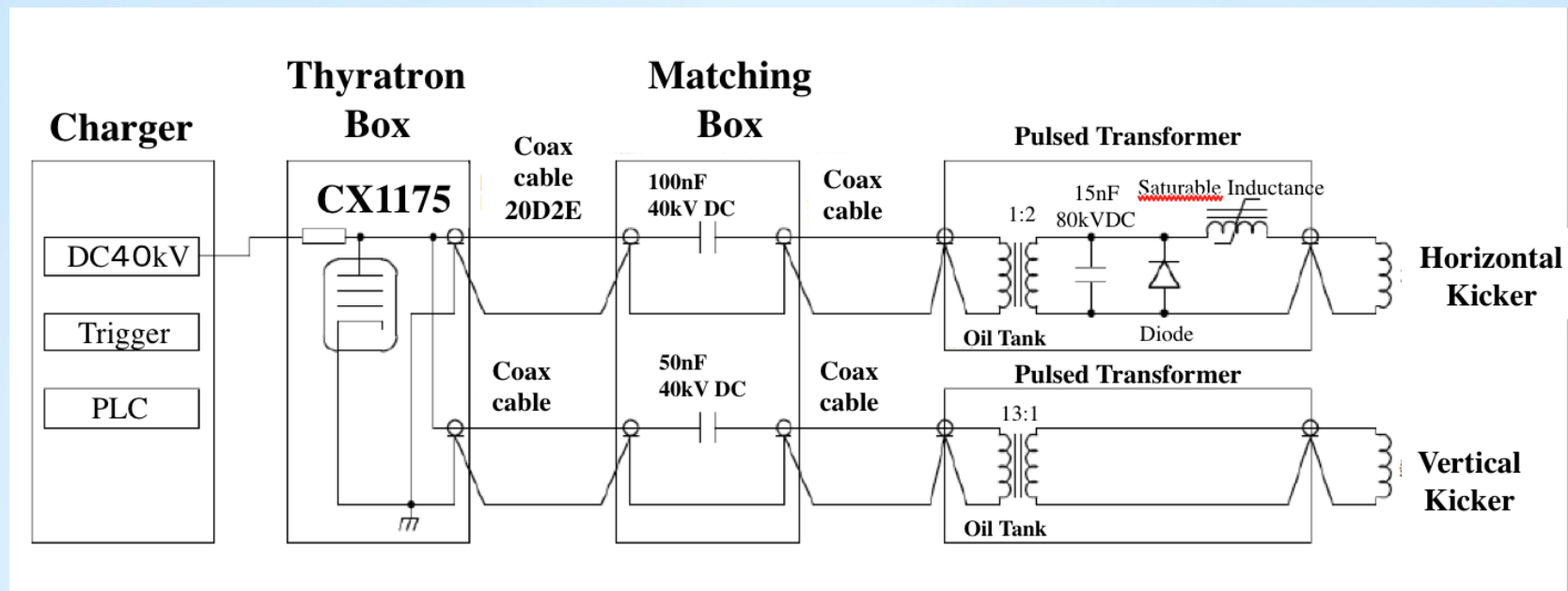
Optics

- ★ Kicker and Pulsed Quadrupole Magnets
- ★ Power Supply
- ★ Ceramic Chamber
 - -> Spattering
- ★ Extraction Window

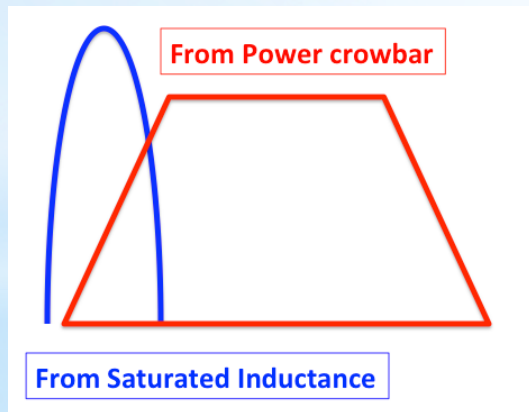
Developments of Hardware

	HER			LER		
	H	V	Q	H	V	Q
θ (mrad)	2.3	0.35	-	1.68	1.05	-
B (T,T/m)	4.09e-2	2.5e-2	1.5 (B')	3.3e-2	4.1e-2	1.5(B')
I total (kA) (/coil)	9.2 (2.3)	0.47	11.7 (2.2)	3.6 (1.8)	0.8	4.3 (2.15)
Gap (mm)	70	70	35 Bohr Rad	70	70	42.5 Bohr rad
L of Ferrite	400x4	400x1	400x8	350x2	350x1	400x2
# of coil	4	1	8	2	1	2
L of Ceramic	500x4	500x1	500x8	500x2	500x1	500x2

Abort Kicker and Pulsed Quadrupole magnet Specifications



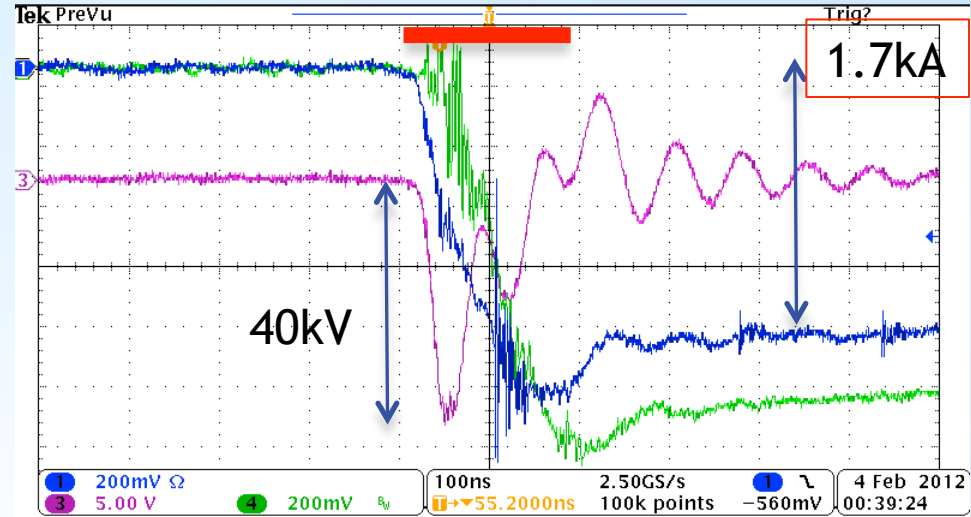
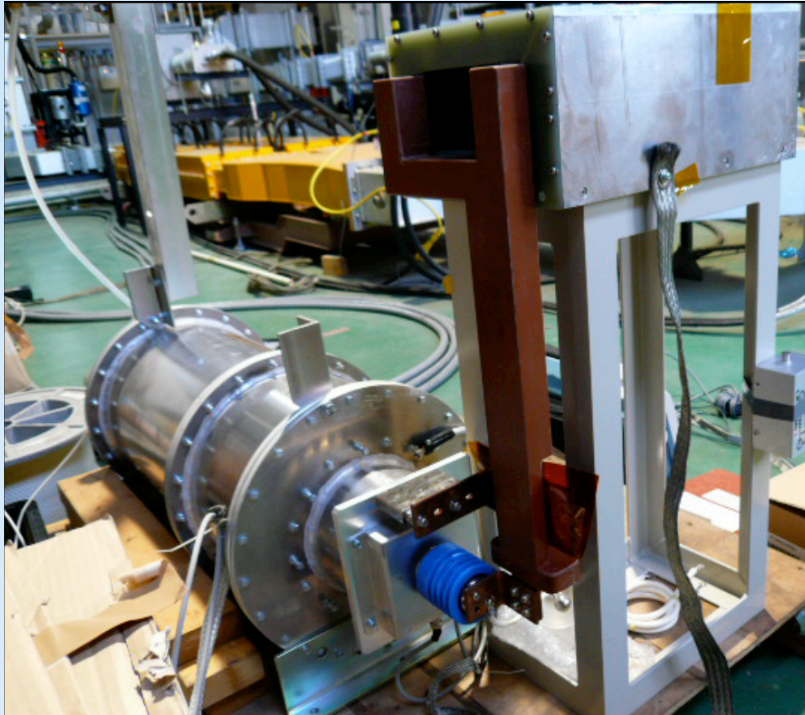
Saturable Inductance + Power Crowbar Circuit



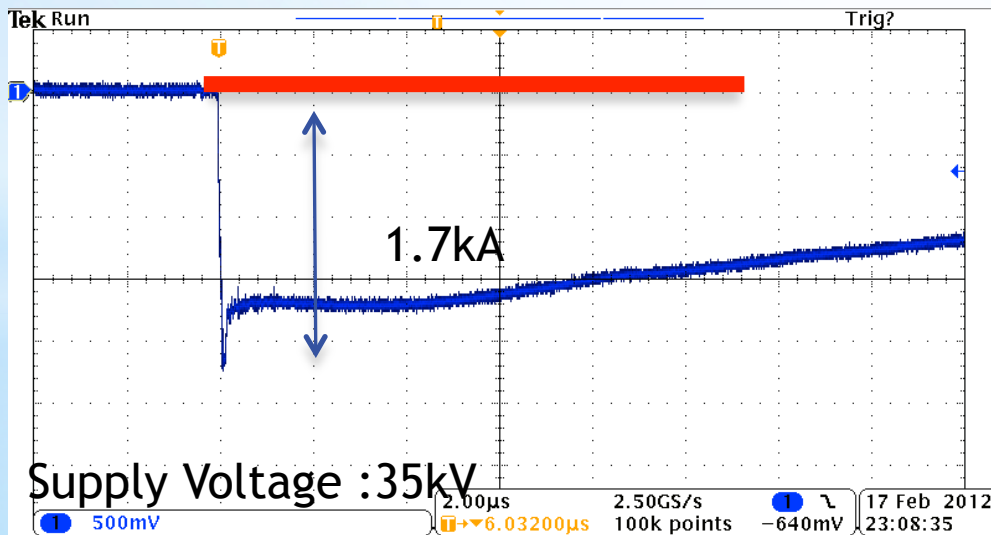
Free-wheeling diode, which reduces the pulse through the primary switch quite a lot

* Rise Time 120nsec

Magnet and Power Supply

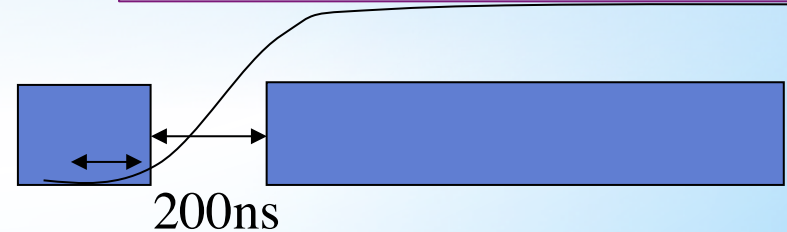


- Magnet Current = 1.7kA (Flat Top)
- Magnetic Field
- Coil Voltage (40kV)



Supply Voltage : 35kV

- Issues:
- (1) Response time of power crowbar circuit is still slow
 - (2) Diode "ON" resistance of the power crowbar is still large



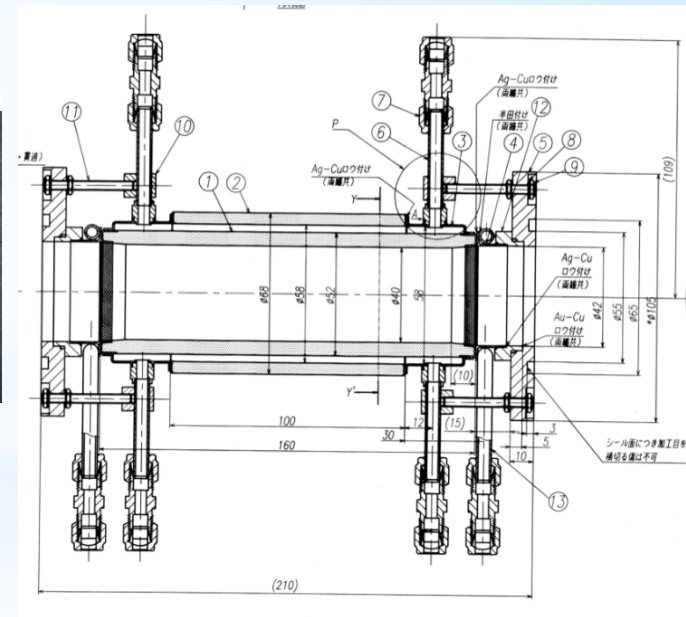
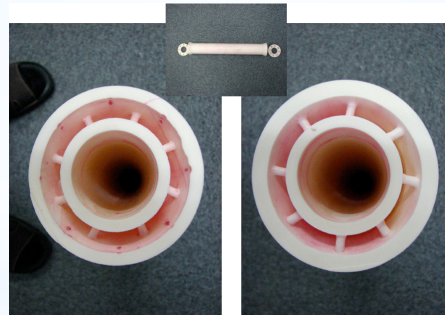
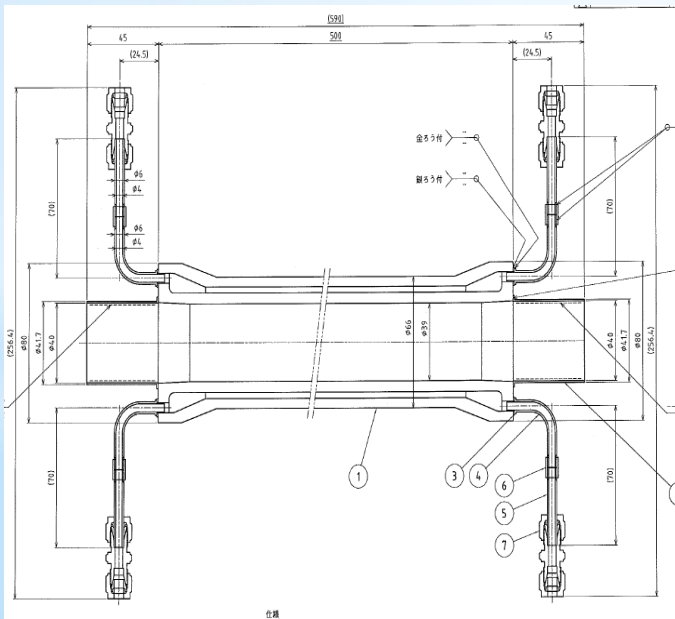
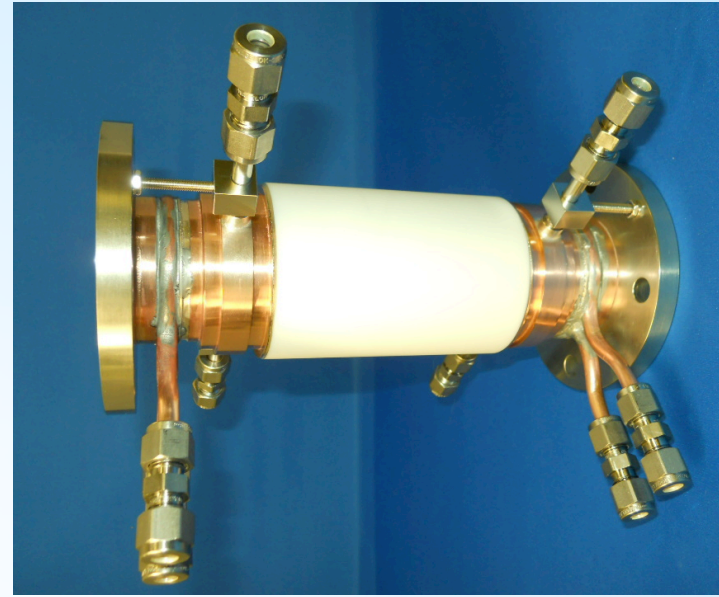
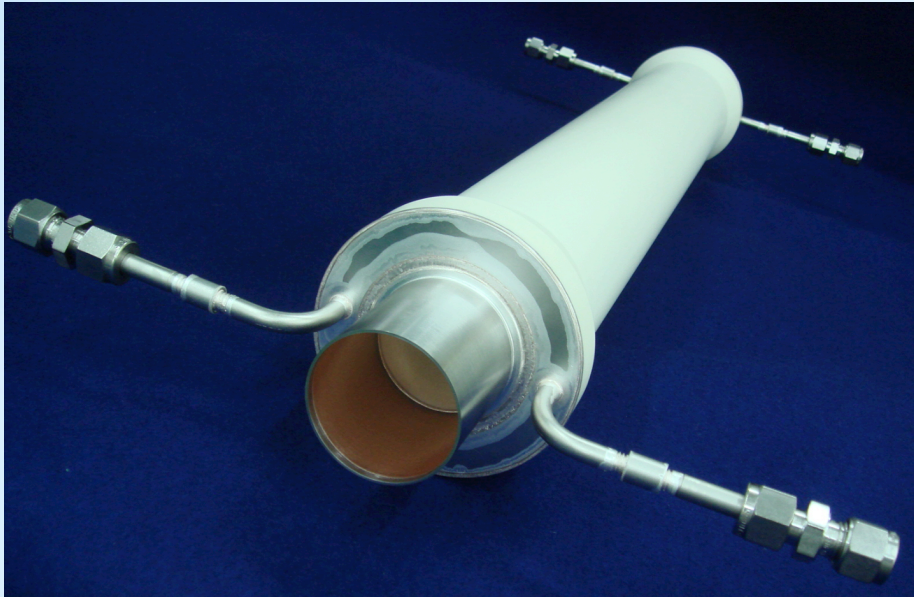
Development of water cooling ceramic chamber

-> Compact Chamber (Kicker Gap 90mm->70mm)

-> Cu coating in side the Kovar sleeve (100um)

Length of Ceramic	500mm
Estimated power loss	~1kW
Ti coating thickness (Inner wall of Ceramic)	6μm
Cu coating thickness (Inner wall of Kovar sleeve)	>100μm
Inner wall	Race Track 60x40 (LER)
	Circle r=40 (HER)

Ceramic Chamber



Single Ceramic : Hollow Type ceramic

Double tube structure brazing side of ceramic.

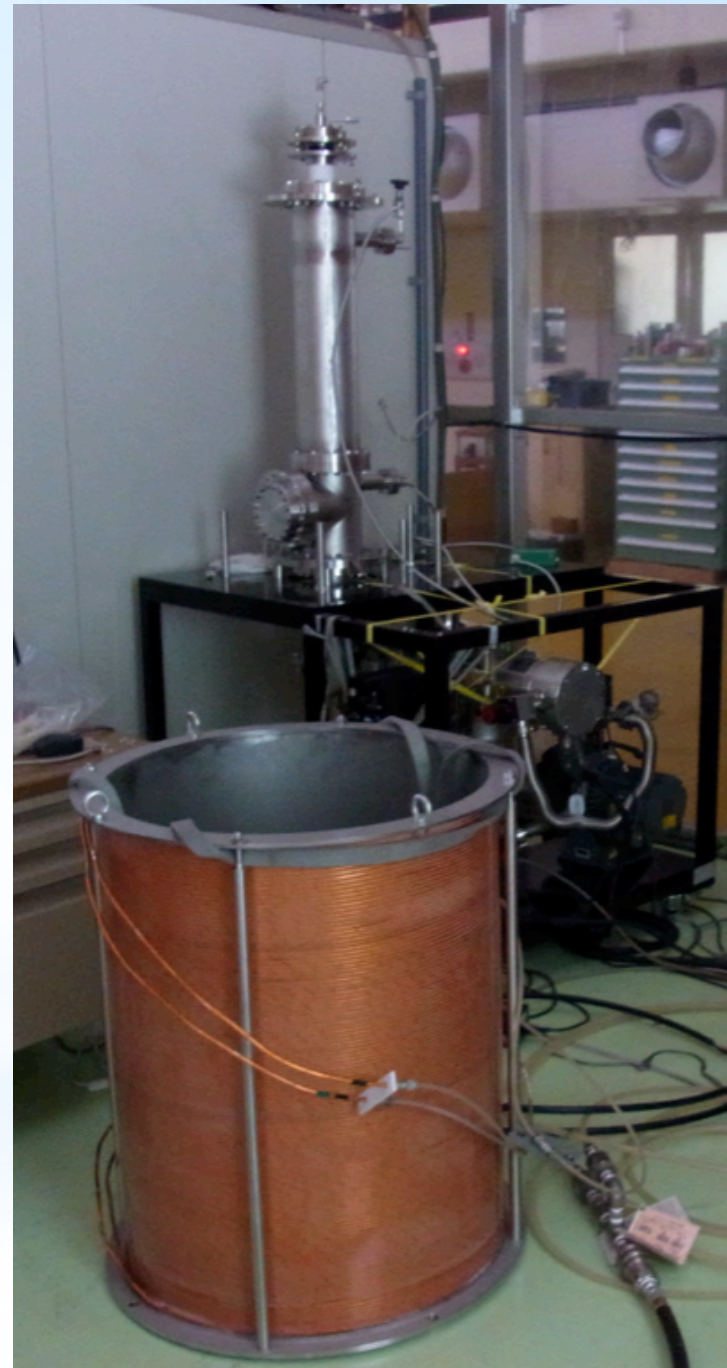
For the Ti coating of inner wall
of the ceramic chamber

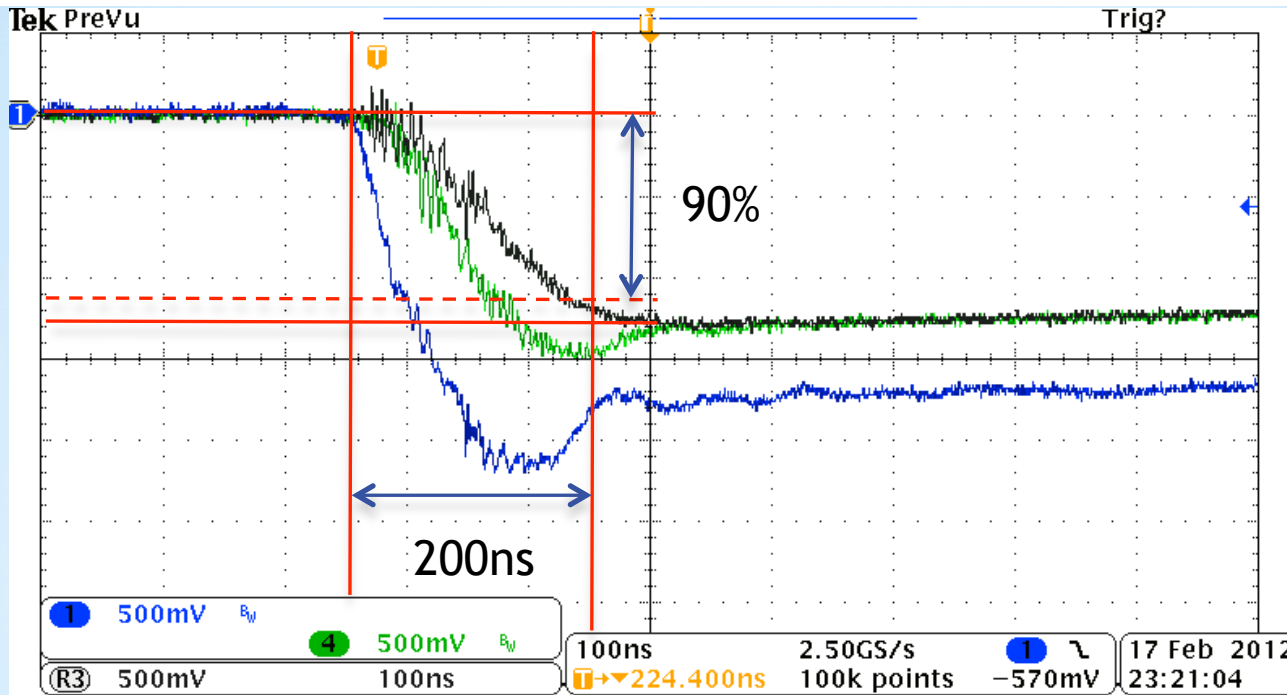
Spattering

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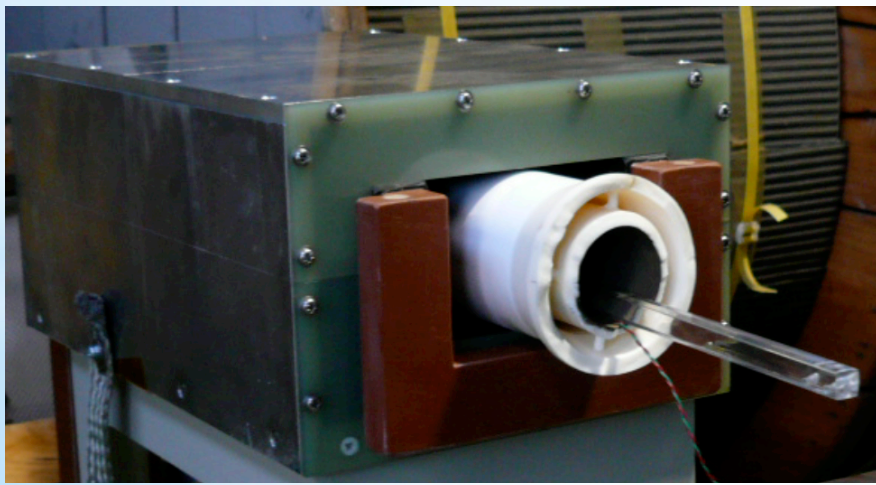




Current of the coil

Magnetic Field
With chamber

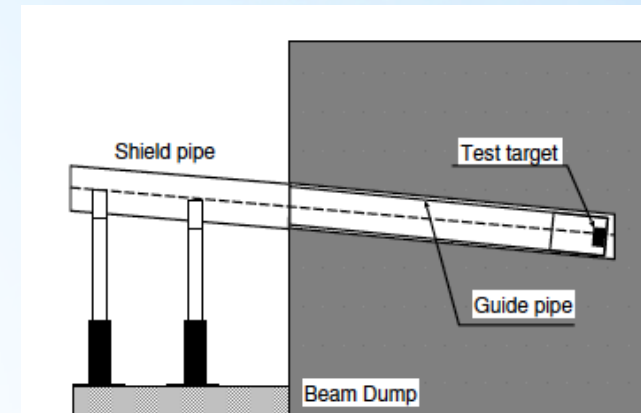
Magnetic Field
Without chamber



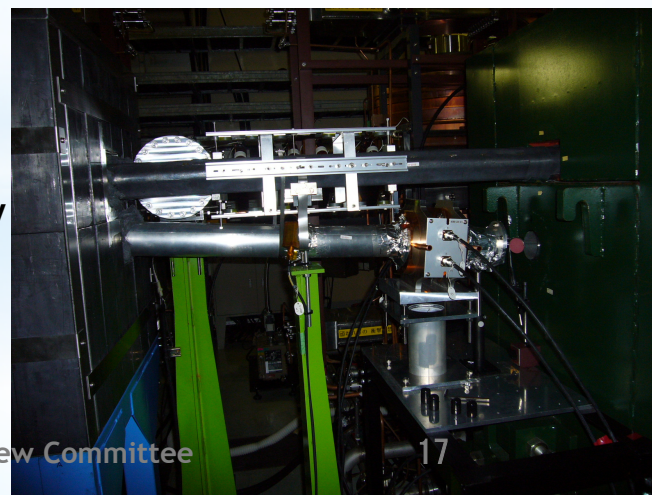
Delay of the Magnetic Field

An Accelerator Study for Ti Extraction Window

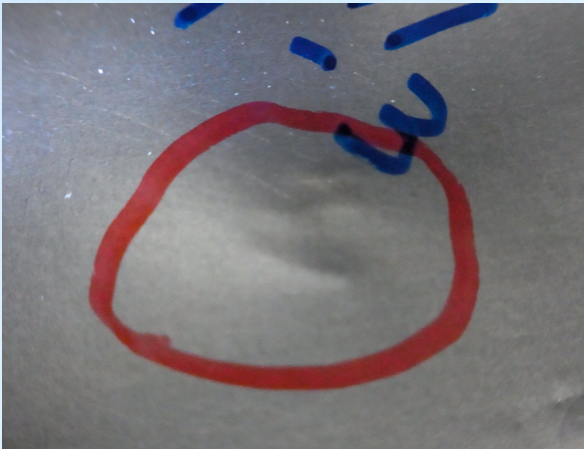
1100mA 7GeV



Ti
And
Ti Alloy

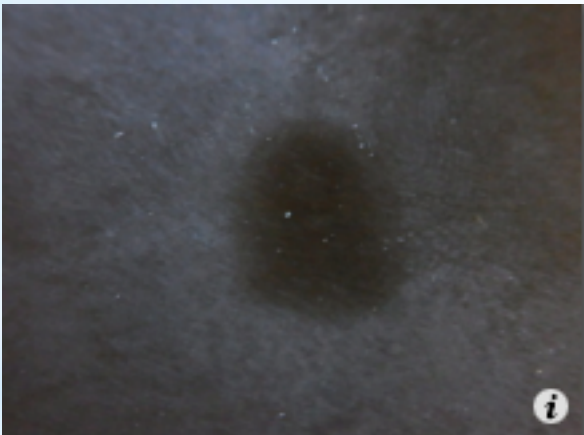


Ti Plate
#7



Ti alloy 0.1mm

Ti Plate
#8



Ti alloy 1 mm



Ti 0.1mm

Ti Plate
#7



Ti 1mm

Ti Plate
#8

Ti VS Ti Alloy

Damages of Ti Plate

@1.1A HER

# Ti Plate	Radiation Length (Fe)	Energy Deposit	δX	δT Ti	Current Density	Ti Alloy (1mm)	Ti (1mm)
	0	4.9	1.17	58	0.5	○	○
	0.25	6.8	1.17	80	0.8	-	-
0	0.5	11.4	1.17	134	1.3	○	○
1	0.75	18.7	1.17	220	2.1	○	○
2	1.0	28.6	1.17	338	3.3	○	○
3	1.25	41.2	1.17	485	4.8	○	△
4	1.5	56.5	1.17	666	6.5	△	×
5	1.75	74.5	1.17	880	8.4	△	×
6	2.0	95.2	1.17	1123	10.9	△	×
7	2.25	118.5	1.17	1399	21.2	△	×
8	2.5	144.6	1.17	1705	25.8	△	×

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×: Damaged (uneven) ○: OK

△ : There is a mark but not bulge. (Flat surface)



Ti 1mm



Ti 0.5 mm



Ti 0.2mm

Damage of Ti Plate Thickness dependence

	Ti
melting point	1941
boiling point	3560
specific heat	0.52

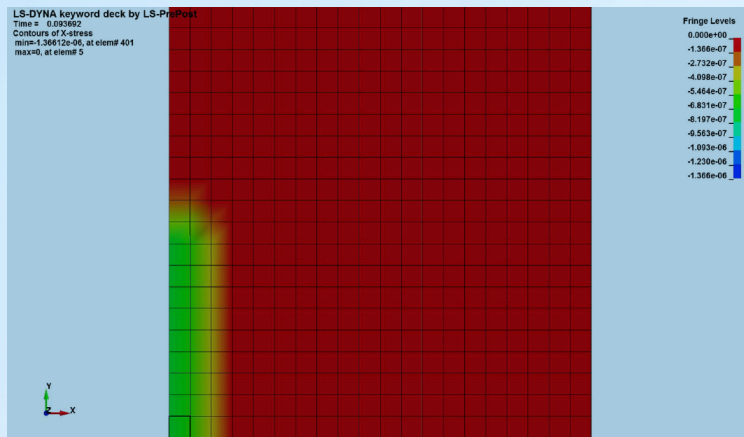
Thickness Dependence of Ti Plate Damage

# Ti Plate	δT Ti	Ti Alloy (mm)				Ti (mm)			
		1	0.5	0.2	0.1	1	0.5	0.2	0.1
	58	○	-	-	-	○	-	-	-
	80	-	-	-	-	-	-	-	-
0	134	○	-	-	-	○	-	-	-
1	220	○	-	-	-	○	-	-	-
2	338	○	○	△	△	○	○	○	○
3	485	○	○	-	-	△	△	-	-
4	666	△	○	×	×	×	△	×	×
5	880	△	-	×	-	×	-	×	×
6	1123	△	△	-	-	×	△	×	×
7	1399	△	-	-	×	×	-	-	×
8	1705	△	△	×	×	×	△	×	×

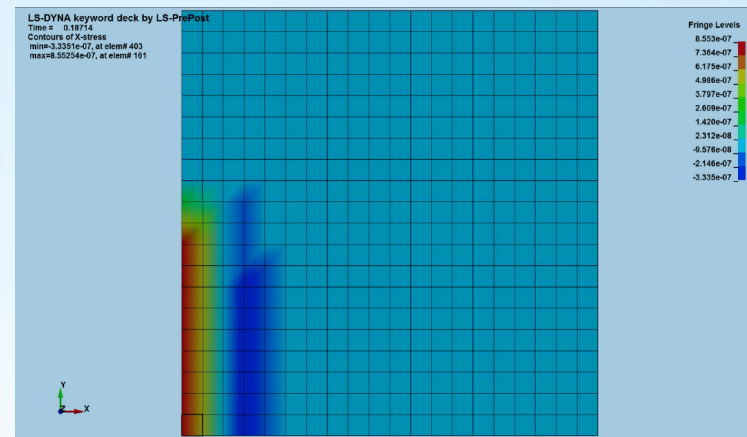
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×: Damaged ○: OK
 △ : There is a mark but not bulge.

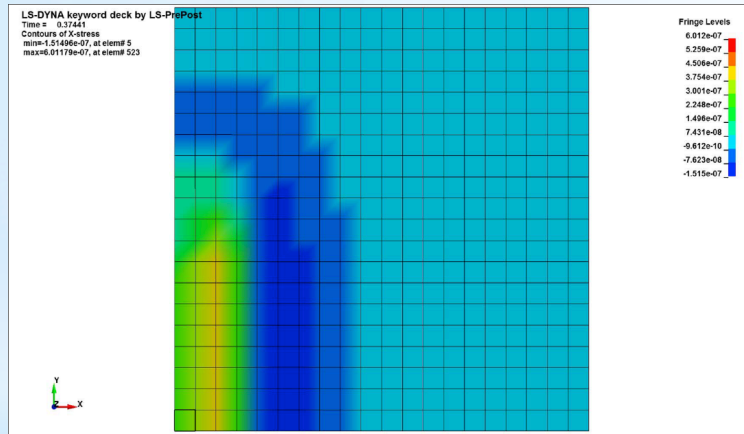
Terui



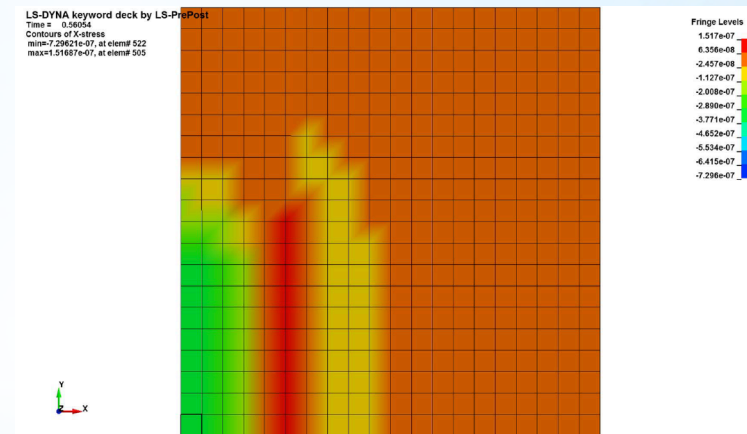
T=0.093



T=0.187



T=0.374



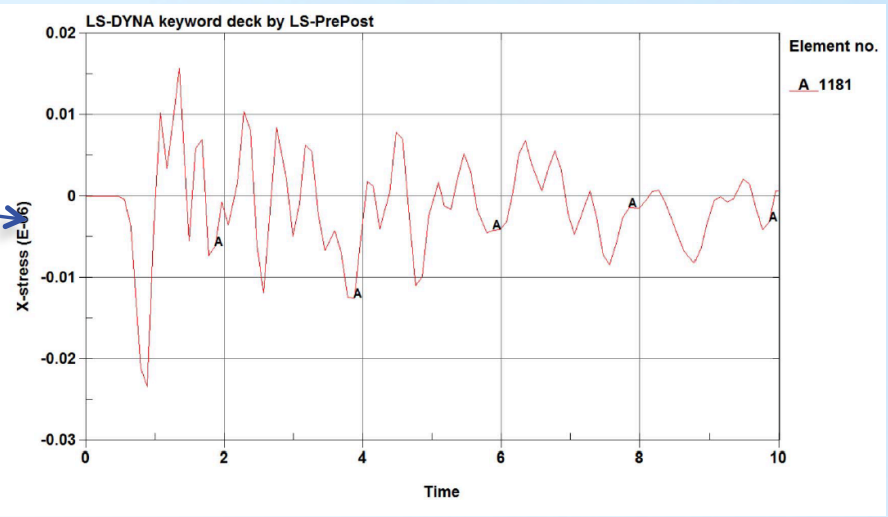
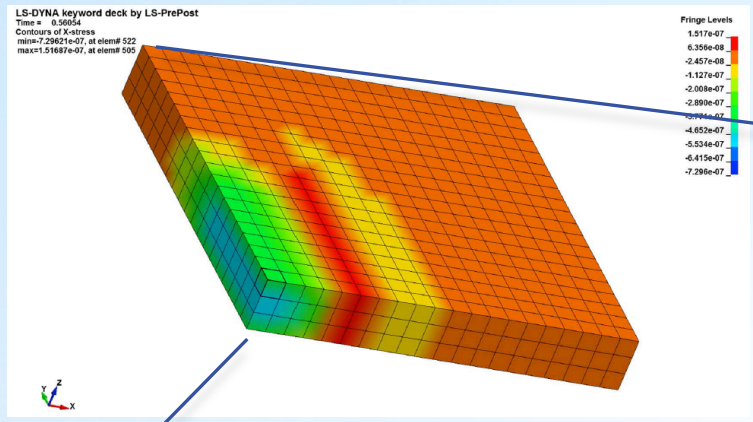
T=0.581

1/4 Model

Gives 500°C heat to the 1x10 mm area (T=0) and calculate stress propagation

Simulation of the window

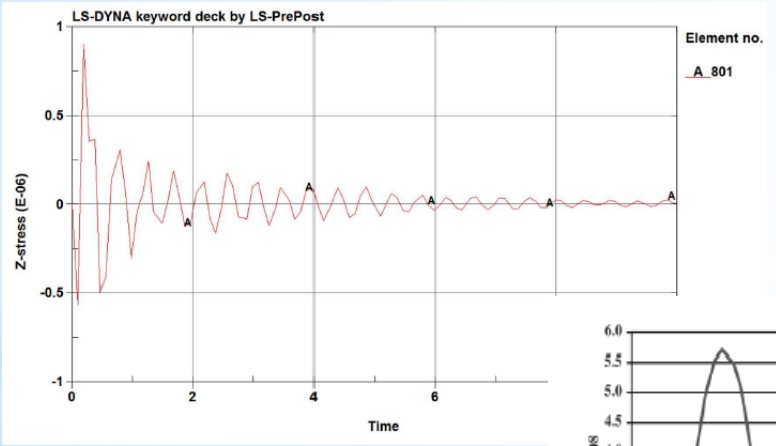
From Mr. Terui



Stress versus time

(W.Stein et al Proc. Of the 2001 PAC, Chicago)

- ★ Energy deposit - psec
- ★ Temperature rise - nsec
- ★ Stress - 200-300nsec
- ★ The temperature profile of a spot requires about 1 sec to relax down to initial temperature



Z-direction Stress

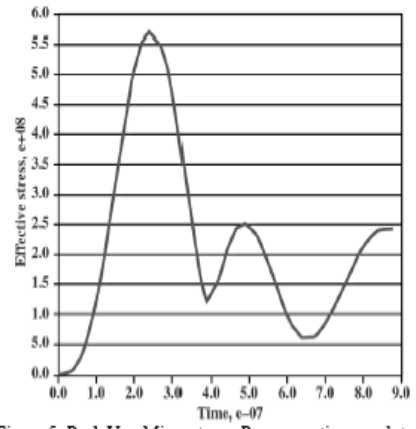
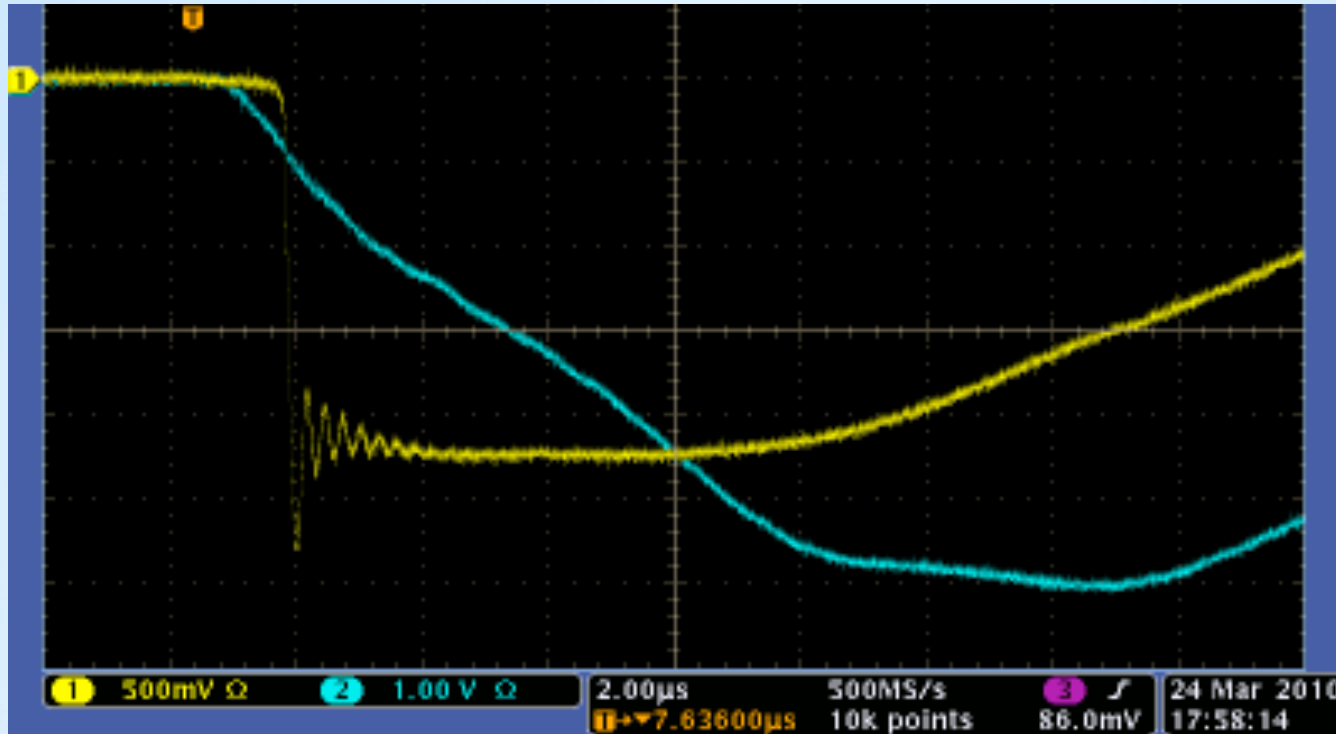


Figure 5: Peak Von Mises stress, Pa, versus time, s, plot.

- ✦ Possibility to use two Sextuple Magnets instead of Pulsed magnets to enlarge the horizontal beam size at the extraction window
- ✦ Optimize the thickness of the inner Ti coating of the ceramic chamber
- ✦ Need to understand the Ti window damage process.
- ✦ The vertical beam moving is necessary to diffuse heat on the window, and do we need the horizontal beam moving ?
- ✦ Because of bad economic situation, the company TDK won't produce Ferrite core any more. We have to look for the company that make ferrite core for us. We hope our government won't cut 7.8 % of our salary, we will buy the product of TDK.

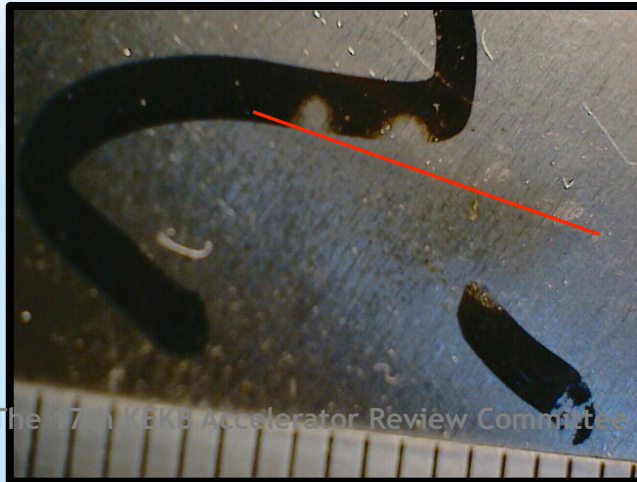
Issues and Discussions

*Backup



Vertical Kicker and Horizontal Kicker current

* Damage of Ti plate



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